



ISSM2014 Financial SPONSORSHIP LEVELS
Information
December 2-3, 2014, Tokyo, Japan

Since its start in 1992 in Japan, ISSM has provided unique opportunities to share semiconductor manufacturing technology "best practices" for the benefit of professionals worldwide. At the symposium, semiconductor manufacturing professionals gather together to seriously discuss presented technologies developed because of the world wide need for semiconductor manufacturing technology advancement. The 22nd annual ISSM will be held in Tokyo, Japan in cooperation with e-Manufacturing & Design Collaboration Symposium (eMDC) which is sponsored by TSIA with support from SEMI and GSA. It is crucial to re-examine semiconductor manufacturing in terms of fundamental principles in order to continue scaling beyond the 20nm/20nm nodes in the coming Internet of Things era. In addition, manufacturing technologies for preserving the earth's environment have become new challenges. These manufacturing technology challenges show the need for drastic revolutionary thought and stronger collaborative efforts to find solutions to the pre-competitive challenges. With strong partnership, ISSM and TSIA endeavor to bring together all scientists, researchers and experts from various areas to share their latest developments, break-through advancements, practical experiences and innovative ideas. The program will feature keynote speeches by world leading speakers, timely and highlighted topics and networking sessions focusing on equipment/materials/software/services with suppliers' exhibits. ISSM continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We invite you to share your professional experiences at the 22nd annual International Symposium on Semiconductor Manufacturing.

Date: December 2-3, 2014
Location: Hyatt Regency Tokyo
<http://tokyo.regency.hyatt.com/>
2-7-2 Nishi-Shinjuku, Shinjuku-Ku
Tokyo 160-0023, Japan
Tel: +81 3 3348 1234
Fax: +81 3 3344 5575

Sponsored by: The Japan Society of Applied Physics
Co-sponsored by:

The Institute of Electrical and Electronics Engineers, Inc. (IEEE)
IEEE Electron Devices Society (EDS)
Minimal Fab Development Association
Semiconductor Equipment and Materials International (SEMI)
Taiwan Semiconductor Industry Association (TSIA)

Area of Interest:

Factory Design & Automated Material Handling(FD)
Manufacturing Strategy and Operation Management (MS)
Manufacturing Control and Execution (MC)
Environment, Safety and Health (ES)
Process and Material Optimization (PO)
Yield Enhancement Methodology (YE)
Contamination Control and Ultraclean Technology (UC)
Process Control and Monitoring (PC)
Process and Metrology Equipment (PE)
Design for Manufacturing (DM)
Final Manufacturing (FM)

Highlight Theme

Big Data
3DIC (TSV and all other 3D)
Power Devices
Printed Electronics

Financial Sponsorship of ISSM2014 in Tokyo

	Platinum Sponsor	Gold Sponsor	Silver Sponsor	Bronze Sponsor
Sponsorship Fee	¥800,000	¥600,000	¥400,000	¥200,000
ISSM2014 Invitation (Free)				
Free ticket(s) for ISSM2014	6	4	2	1
ISSM2014 Website				
Company logo placed on ISSM2014 website	Yes	Yes	Yes	Yes
	Upper	Middle	Lower	Lower
Link to corporate website	Yes	Yes	Yes	Yes
ISSM2014 Proceedings				
Recognition of sponsorship in meeting materials along with company logo and link to corporate website	Yes	Yes	Yes	Yes
Company logo printed in color on the brochure on site	Yes	Yes	Yes	Yes
ISSM2014 Screen at site				
Company logo on the screen of interval	Yes	Yes	Yes	Yes
Company logo poster at the Symposium Room	Yes	Yes	Yes	Yes
Table top exhibition				
Provide table and white board at the Room	Yes	Yes	Yes	Yes

【ISSM Japan Office at Semiconductor Portal, Inc.】

E-mail: issm_2014@semiconportal.com

Phone: +81-3-5733-4971

FAX: +81-3-5733-4973